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(12) **United States Design Patent**
Feng

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(54) **LIGHT EMITTING DIODE CHIP**

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- (71) Applicant: **Formosa Epitaxy Incorporation**,
Taoyuan County (TW)
- (72) Inventor: **Hui-Ching Feng**, Taoyuan County (TW)
- (73) Assignee: **Formosa Epitaxy Incorporation**,
Taoyuan (TW)
- (*) Notice: This patent is subject to a terminal disclaimer.
- (**) Term: **14 Years**
- (21) Appl. No.: **29/489,894**
- (22) Filed: **May 5, 2014**

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Primary Examiner — Selina Sikder

(74) *Attorney, Agent, or Firm* — Jianq Chyun IP Office

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(52) **U.S. Cl.**
USPC **D13/180**

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 H01L 27/156; H01L 31/02; H01L 33/00;
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 H01S 5/34; F21K 9/00; F21K 9/30; F21K
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See application file for complete search history.

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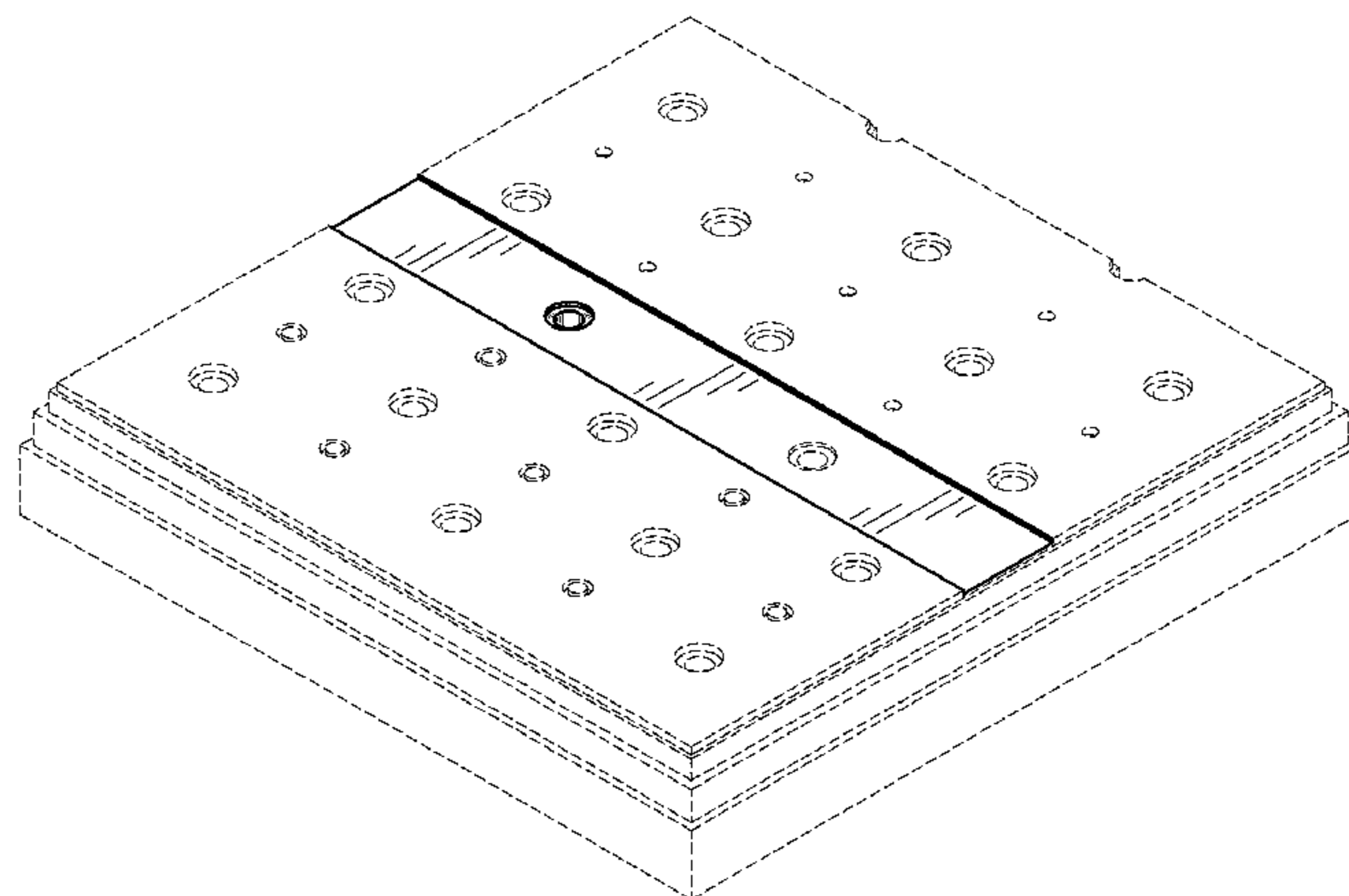
CLAIM

The ornamental design for a light emitting diode chip, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a light emitting diode chip showing an embodiment of my new design;
 FIG. 2 is a front view of the embodiment;
 FIG. 3 is a rear view of the embodiment;
 FIG. 4 is a left side view of the embodiment;
 FIG. 5 is a right side view of the embodiment;
 FIG. 6 is a top view of the embodiment; and,
 FIG. 7 is a bottom view of the embodiment.
 The broken line portions of the light emitting diode chip in FIGS. 1-7 represent unclaimed portions of the design and form no part thereof.

1 Claim, 5 Drawing Sheets



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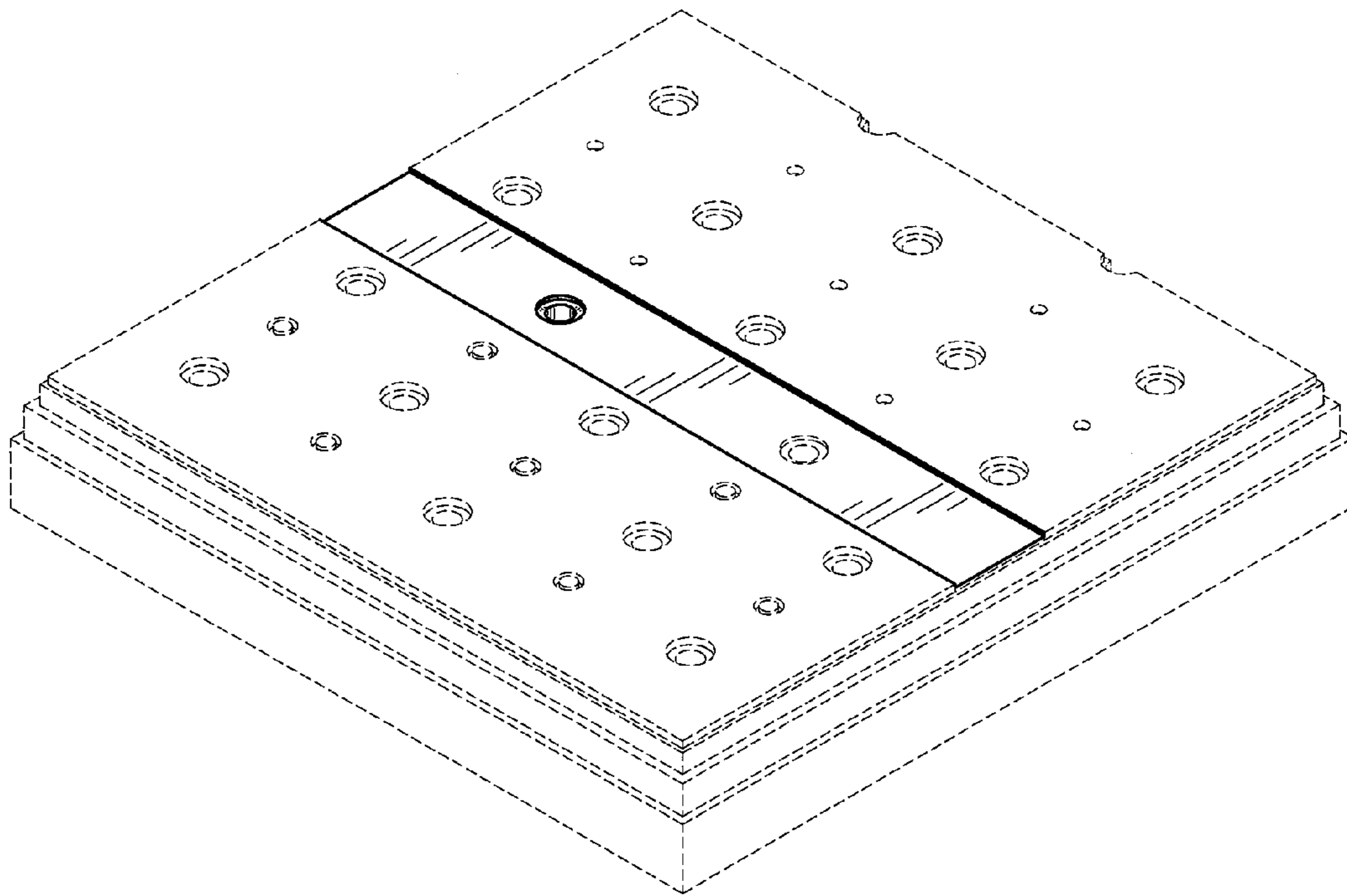


FIG. 1

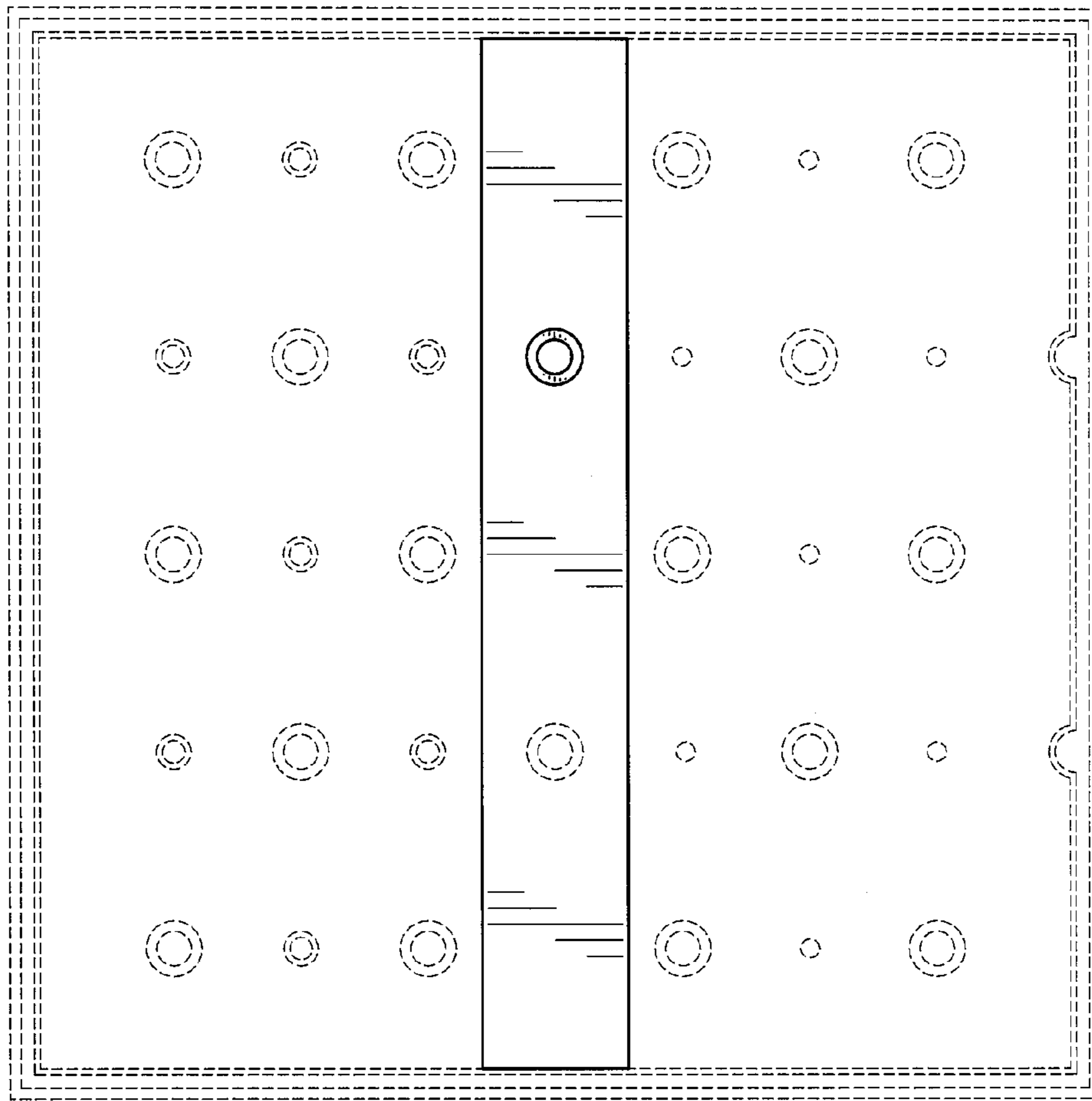


FIG. 2

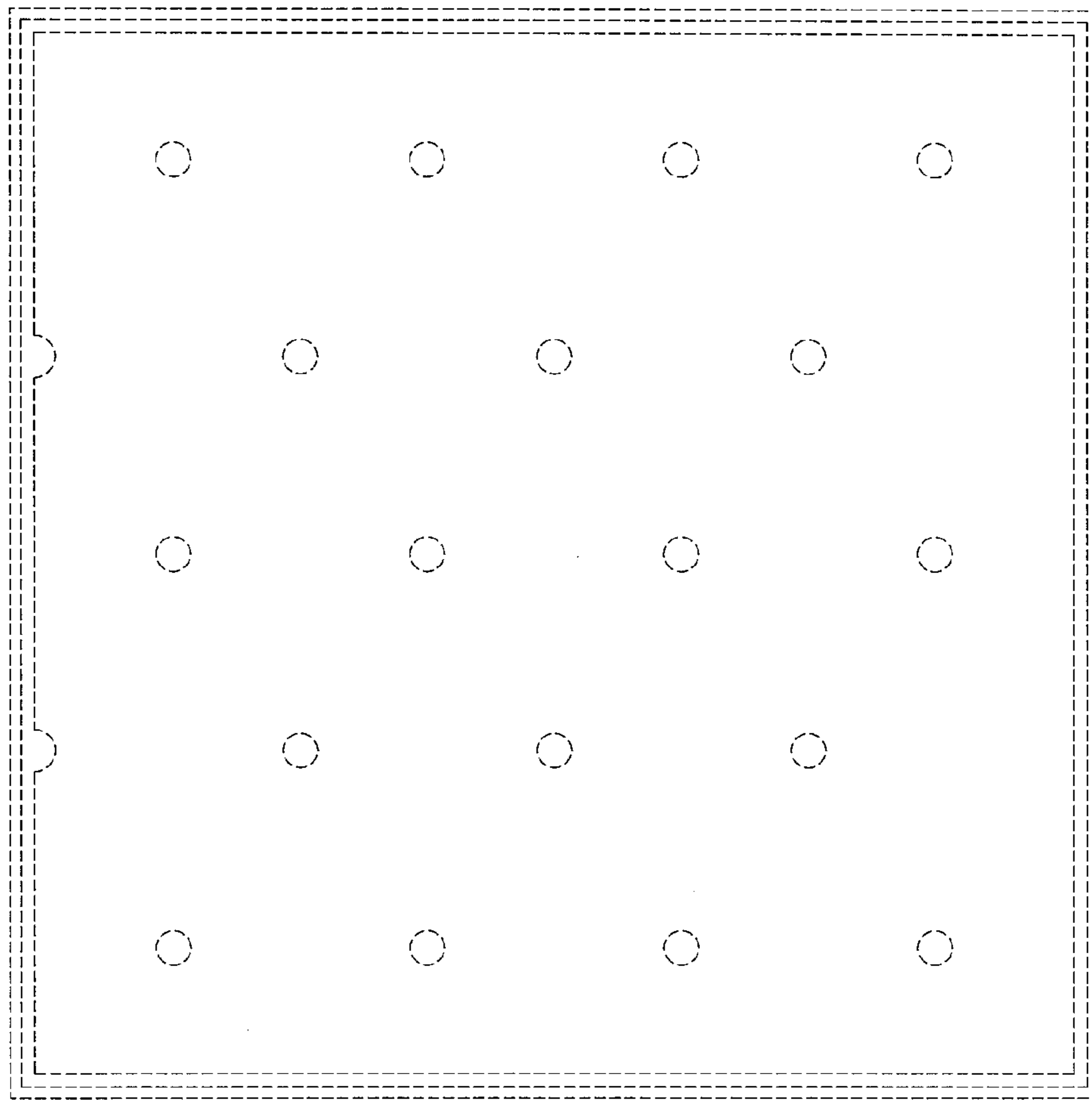


FIG. 3

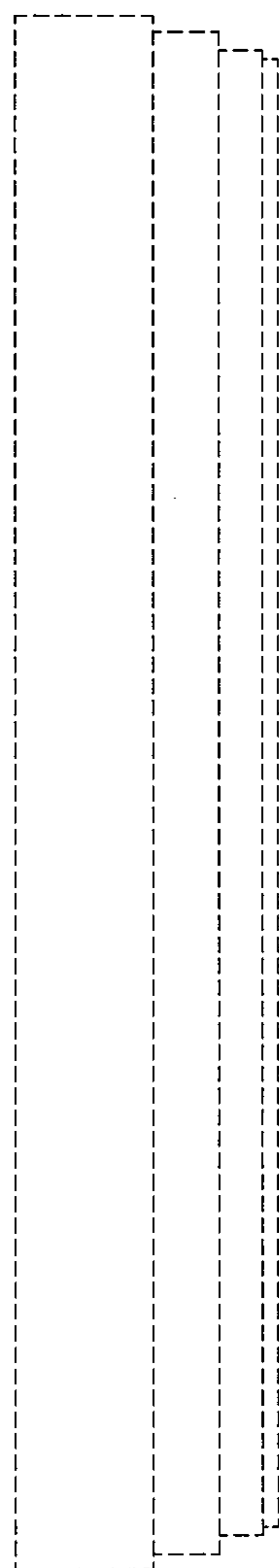


FIG. 4

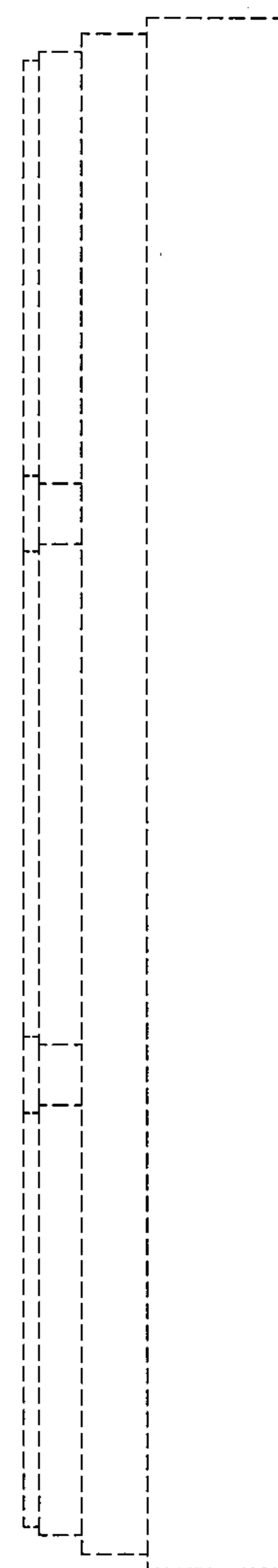


FIG. 5

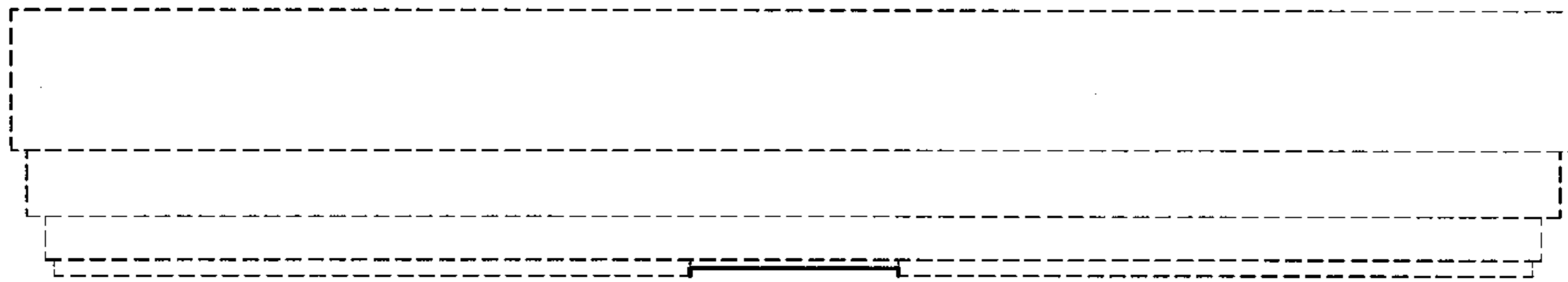


FIG. 6

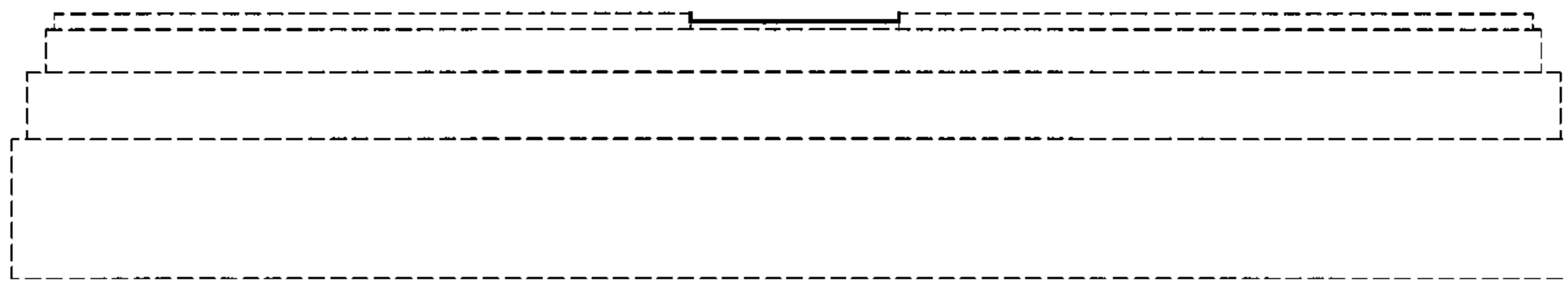


FIG. 7